Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0301-01** DATE: 4/9/2003
Product Affected:
IDT72V3611, IDT72V3612, IDT72V3613, IDT72V3614

Date Effective: 7/9/2003

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ☒ Date Code
- ☐ Other

Contact: Dasharath Patel
Title: Quality Assurance Manager
Phone #: (408) 330-1488
Fax #: (408) 330-1450
E-mail: Dasharath.Patel@idt.com

Attachment:: ☒ Yes ☐ No

Samples: Available now

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☒ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

As a part of IDT's consolidation of wafer fab manufacturing operations, the devices listed above are transferred from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR). There will be no change in manufacturing technology. Starting 07/09/2003, customers will receive material manufactured either at FAB 2 or FAB 4. Please see below for means of distinguishing inventory.

Fab2 material mark	Z-Step	Date Code:	Zyyww
Fab4 material mark	Y-Step	Date Code:	Yyyww
		yy: Year	ww: Work Week

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification summary

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0301-01

PCN Type:	Wafer Fabrication Site Change
Data Sheet Change:	None
Detail of Change:	Transfer of manufacturing site from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR) for the following devices: IDT72V3611, IDT72V3612, IDT72V3613 and IDT72V3614

Conversion schedule (Estimated)

Samples	Available upon request
Production Shipments	7/9/2003

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0301-01

Qualification Plan: **QFI-02-16**

Test Vehicle: IDT72V3614

Test Description/Condition	Test Methods	SS /# Fails	Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116 / 0
Latch-Up Immunity (+ - I and V stress, + - 100 mA Trigger)	EIA/JESD 78	10/0	10 / 0
ESD Human Body Model	MIL-STD-883, Method 3015	9/0	9 / 0
ESD Charge Device Model	JESD22-C101	6/0	6 / 0

Characterization Data:

Characterization data is available upon request.